1. Record Nr. UNINA9910815642003321

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Titolo	The ESD handbook / / Steven H. Voldman
Pubbl/distr/stampa	Hoboken, New Jersey ; ; West Sussex, England : , : Wiley, , [2021] ©2021
ISBN	1-119-23310-0
Descrizione fisica	1 online resource (1,574 pages) : illustrations
Disciplina	537.52
Soggetti	Electric discharges
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
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